



# WOOD H110 ECO PARQUET

## HYBRID ADHESIVE FOR LAYING ENGINEERED WOOD FLOORING

### KEY BENEFITS

- **Solid wood planks up to 110 mm wide and 15 mm thickness**
- **For engineered parquet, all formats**
- **Fast blocking**
- **Suitable for underfloor heating,**



### APPLICATIONS

#### DESCRIPTION

**WOOD H110 ECO PARQUET** is hybrid adhesive for laying all types of engineered and solid wood floors. Solid parquet up to 110mm wide.

#### APPROVED COVERINGS

- Engineered parquet in all formats,
- Mosaic parquet,
- Wood on edge,
- End grain wood
- Solid parquet up to 110mm wide

#### SUITABLE SUBSTRATES

- Surfaced concrete with a smooth finish.
- Cement-based screeds
- Anhydrite screeds.
- Old ceramic tiles, suitably smoothed.
- Old parquet flooring on joist.
- Particle board or plywood, OSB3.
- Suitable for underfloor heating (check with your local technical/sales rep for further details)

### PRODUCT CHARACTERISTICS

<b>Colour</b>	Creme beige
<b>Density</b>	≈ 1,60 ±0,1
<b>Application temperature</b>	+10°C to +30°C
<b>Consumption</b>	800-1200 g/m <sup>2</sup>
<b>Open time**</b>	Approx. 40 min
<b>Blocking time**</b>	Approx. 2 hours
<b>Open to traffic**</b>	Foot traffic: 24 hours High traffic: 48 hours
<b>Curing time**</b>	24 to 48 hours
<b>Sanding and varnishing**</b>	After 48 hours
<b>Storage / Shelf life*</b>	18 months

\*from date of manufacture in original, unopened packaging, clear of the ground, in cool, dry conditions within the temperature range +5°C to +25°C and out of direct sunlight. Protect from frost, damp, condensation and dew.

\*\* these times are determined at + 23° C and 50 % relative humidity on normally absorbent substrates

## DIRECTION FOR USE

### PREPARATION

Ensure the subfloor is in accordance with building standards. Subfloors must be clean, sound, dry (<75%RH), and free from contaminants that may impair adhesion e.g. dust, grease, paint, plaster, polish, water softenable adhesive etc.

Ensure the timber is acclimatized in accordance to the manufacturer's instructions in the environment in which it is to be laid. Always allow an expansion gap around any perimeters or columns to allow for natural movement of the wood when bonded. Store the adhesive in a temperate room.

For subfloors that are not sufficiently smooth or require height build up to receive the particular floor covering being bonded, an application of a suitable Bostik smoothing compound and primer system is recommended. Please consult Technical Services for advice on specific products and subfloors.

Before applying any adhesive, ensure the substrate is dry and dust free.

#### Underfloor heating systems:

Underfloor heating systems must be switched off for 48 hours before installation. Wait 7 days after installation before gradually turning up underfloor heating.

### APPLICATION

Apply the glue with a suitable spatula to the surface, using a single application method, at a rate of approximately 1000 to 1200g/m<sup>2</sup>, depending on the roughness of the surface and the type of parquet to be glued

Notch. Trowel	Consumption g/m <sup>2</sup>	Type of parquet
B5	800 - 900	Mosaic parquet, Cork/rubber underlayment
B11	900 -1000	Engineered parquet up to 110mm wide / 15mm thick
B12	1000 - 1200	All format engineered parquet. Solid parquet up to 110 mm wide / 15 mm thick

Place the wooden planks into the adhesive while it is still fresh. Only apply enough to work within in 40 minutes.

Press firmly to ensure a good glue transfer to the back of the boards, which should be over 80%. Distorted floorboards need to be weighted until the adhesive is fully cured.

Press firmly the parquet to ensure full transfer and collapse the ridges for proper bonding. Pay attention to details:

- Respect the peripheral gaps (8mm minimum).
- The rule for calculating gaps is 0.15% of each of the largest dimensions to be covered by the parquet.

### DRYING TIMES

The bonded wood should be open for foot traffic after 24 hours. Leave at least 24 hours curing time before sanding and varnishing.

### CLEANING

Clean tools and equipment with cleaning wipes or white spirit immediately after use. Cured adhesive can only be removed mechanically.

Code	UC	PALLET.	PCB	GENCOD
30626113	21 kg	1	24	3549212492755



### SAFETY

For more details, consult the safety data sheet on <https://bostikdsd.thewerco.com/default.aspx>

*The information given and recommendations made herein are based on Bostik's research only and are not guaranteed to be accurate. The performance of the product, its shelf life, and application characteristics will depend on many variables, including the kind of materials to which the product will be applied, the environment in which the product is stored or applied, and the equipment used for application. Any change in any of these variables can affect the product's performance. It is the buyer's obligation, prior to using the product, to test the suitability of the product for an intended use under the conditions that will exist at the time of the intended use. Bostik does not warrant the product's suitability for any particular application. The product is sold pursuant to Bostik's Terms and Conditions of Sale that accompanies the product at the time of sale. Nothing contained herein shall be construed to imply the nonexistence of any relevant patents or to constitute permission, inducement, or recommendation to practice any invention covered by any patent, without authority from the owner of the pat*

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